1. A polishing device for partially polishing a substrate, comprising:

a rotatable polishing member having a processing surface which comes into contact with the substrate and which is smaller than the substrate;

a conditioning member for performing conditioning on the polishing member;

a first pressing mechanism for pressing the conditioning member against the polishing member in polishing the substrate; and

a control unit for controlling an operation of the polishing device, wherein the control unit is configured to control the first pressing mechanism when the substrate is partially polished by the polishing member,

wherein the polishing member is formed into any one of structures including:

(1) a disc shaped or a cylindrically shaped structure, having a center axis parallel to the surface of the substrate;

(2) a conically shaped or a truncated conically shaped structure, having a center axis parallel to the surface of the substrate; and

(3) a spherically shaped or a partially spherically shaped structure,

a rotating axis of the polishing member is parallel to the surface of the substrate.

2. The polishing device according to claim 1, further comprising:

a pressing mechanism for pressing the polishing member against the substrate; and

a first drive mechanism for imparting a motion to the polishing member in a first motion direction parallel to a surface of the substrate.

3. The polishing device according to claim 2, further comprising

a second drive mechanism for imparting a motion to the conditioning member to have a component contained in a second motion direction perpendicular to the first motion direction, and parallel to the surface of the substrate.

4. The polishing device according to claim 3, wherein

the second drive mechanism is configured to impart a linear motion and/or a rotating motion to the conditioning member.

5. The polishing device according to claim 1, wherein

the control unit is configured to control the first pressing mechanism so that the conditioning is performed at a predetermined cycle in polishing the substrate.

6. The polishing device according to claim 1, wherein

the polishing member and the conditioning member are held with a holding arm.

7. The polishing device according to claim 1, further comprising

a collection unit for collecting waste generated from the polishing member in performing the conditioning.

8. The polishing device according to claim 7, wherein

the collection unit includes a suction unit for removing the waste generated from the polishing member through suction in performing the conditioning.

9. The polishing device according to claim 7, wherein

the collection unit includes a scraper or a wiper for collecting the waste generated from the polishing member in performing the conditioning.

10. The polishing device according to claim 7, wherein the collection unit includes

a liquid supply mechanism for cleaning the conditioned polishing member, and

a liquid collection mechanism for collecting the liquid which has been used for cleaning the polishing member.

11. A method for polishing a substrate, comprising:

pressing a polishing member against the substrate, the polishing member having a processing surface which comes into contact with the substrate and which is smaller than the substrate;

polishing the substrate by imparting relative motions to the polishing member and the substrate while pressing the polishing member against the substrate; and

conditioning the polishing member while bringing a conditioning member into contact with the polishing member in polishing the substrate,

wherein the polishing member is formed into any one of structures including:

(1) a disc shaped or a cylindrically shaped structure, having a center axis parallel to the surface of the substrate;

(2) a conically shaped or a truncated conically shaped structure, having a center axis parallel to the surface of the substrate; and

(3) a spherically shaped or a partially spherically shaped structure,

a rotating axis of the polishing member is parallel to the surface of the substrate.

12. The method according to claim 11, further comprising

imparting a linear motion and/or a rotating motion to the conditioning member.

13. The method according to claim 11, further comprising

collecting waste generated from the polishing member while the polishing member is conditioned.